H11SSL-C

Key Features

1. Single AMD EPYC™ 7001/7002* Series Processor (*AMD EPYC 7002 series drop-in
   support requires board revision 2.x)

2. 1TB Registered ECC DDR4 2666MHz SDRAM in 8 DIMMs
   2TB Registered ECC DDR4 3200MHz SDRAM in 8 DIMMs
   (Board revision 2.x required)

3. Expansion slots:
   3 PCI-E 3.0 x16
   3 PCI-E 3.0 x8
   M.2 Interface: 1 PCI-E 3.0 x4
   M.2 Form Factor: 2280, 22110
   M.2 Key: M-key

4. 8 SATA 3.0 + Broadcom 3008 for 8 SAS3 ports, 1 M.2

5. Dual Gigabit Ethernet LAN Ports

6. ASPEED AST2500 BMC graphics

7. Up to 5 USB 3.0 ports
     (2 rear + 2 via header + 1 Type A)
   Up to 4 USB 2.0 ports
     (2 rear + 2 via header)

8. 7 PWM 4-pin Fans with tachometer status monitoring

Note: Image above may show a varied configuration of optional parts.
Please refer to parts list for standard parts included.

Links & Resources

▶ Tested Memory List

▶ Tested HDD List

▶ Tested M.2 List

▶ Tested AOC List

▶ Motherboard Manual

▶ Update Your BIOS

▶ IPMI Firmware

▶ Download the Latest Drivers and Utilities

▶ Download Driver CD

▶ OS Compatibility

Specifications

Product SKUs

MBD-H11SSL-C	▪ H11SSL-C
MBD-H11SSL-C-B	▪ H11SSL-C (Bulk Pack)
MBD-H11SSL-C-O	▪ H11SSL-C (Retail Pack)

Physical Stats

Form Factor	▪ ATX
Dimensions	▪ 12" x 9.6" (30.5cm x 24.4cm)

Processor/Chipset

CPU	▪ Single AMD EPYC™ 7001/7002* series Processor (*Board revision 2.x required) ▪ Socket SP3
Cores	▪ Up to 32 Cores ▪ Up to 64 Cores (Board revision 2.x required)
Chipset	▪ System on Chip

System Memory

Memory Capacity	▪ 8 DIMM slots ▪ Supports up to 1TB Registered ECC DDR4 2666MHz SDRAM in 8 DIMMs ▪ Supports up to 2TB Registered ECC DDR4 3200MHz SDRAM (Board revision 2.x required) ▪ 8-channel memory bus
Memory Type	▪ DDR4 2666 MHz Registered ECC, 288-pin gold-plated DIMMs ▪ DDR4 3200 MHz Registered ECC, 288-pin gold-plated DIMMs (Board revision 2.x required)
DIMM Sizes	▪ 8GB, 16GB, 32GB, 64GB, 128GB, 256GB* (*Board revision 2.x required)
Memory Voltage	▪ 1.2V
Error Detection	▪ Corrects single-bit errors ▪ Detects double-bit errors (using ECC memory)

On-Board Devices

SATA	▪ SATA3 (6 Gbps)
SAS	▪ Broadcom 3008 SAS3 (12 Gbps) controller ▪ RAID 0, 1, 10
IPMI	▪ Support for Intelligent Platform Management Interface v.2.0 ▪ IPMI 2.0 with virtual media over LAN and KVM-over-LAN support ▪ ASPEED AST2500 BMC
Network Controllers	▪ 2 1GbE LAN via Intel® I210 ▪ 1 Realtek RTL8211E PHY (dedicated IPMI)
VGA	▪ ASPEED AST2500 BMC

Input / Output

SAS	▪ 8 SAS3 (12 Gbps) ports
SATA	▪ 8 SATA3 (6 Gbps) ports

Chassis (Optimized for H11SSL-C)

1U	▪ SC813MFTQC-350CB2 ▪ SC813MFTQC-R407CB
2U	▪ SC213AC-R1K23LPB ▪ SC216BE1C4-R1K23LPB ▪ SC825TQC-R740LPB ▪ SC826BE1C4-R1K23LPB
3U	▪ SC836BE1C-R1K23B
4U	▪ SC745BAC-R1K28B2 ▪ SC846BE1C-R1K23B

Server(s) (with H11SSL-C)

Model(s)	▪ AS -2013S-C0R

System BIOS

BIOS Type	▪ AMI 128Mb SPI Flash EEPROM
BIOS Features	▪ Plug and Play (PnP) ▪ DMI 2.3 ▪ PCI 2.2 ▪ ACPI 5.1 ▪ USB Keyboard Support ▪ SMBIOS 3.1.1

Management

Software	▪ Super Doctor 5 ▪ Watch Dog ▪ NMI ▪ SUM ▪ IPMI 2.0, KVM with dedicated LAN
Power Configurations	▪ ACPI Power Management ▪ Power-on mode control for AC power loss recovery

PC Health Monitoring

CPU	▪ Monitors CPU Core Voltages, +1.8V, +3.3V, +5V, +5V standby, +3.3V standby ▪ CPU switching voltage regulator ▪ Supports system management utility ▪ VBAT
FAN	▪ Up to 7-fan status tachometer monitoring ▪ Up to 7 4-pin fan headers ▪ Dual Cooling Zone ▪ Status monitor for speed control ▪ Pulse Width Modulated (PWM) fan connectors
Temperature	▪ Monitoring for CPU and chassis environment ▪ CPU Thermal Trip Support ▪ Thermal control for 7x Fan connectors ▪ I²C Temperature Sensing Logic
LED	▪ CPU / System Overheat LED
Other Features	▪ Chassis Intrusion Detection ▪ Chassis Intrusion Header ▪ UID

Operating Environment / Compliance

LAN	▪ 2 RJ45 Gigabit Ethernet LAN ports ▪ 1 RJ45 Dedicated IPMI LAN port
USB	▪ 5 USB 3.0 ports (2 rear + 2 via header + 1 Type A) ▪ 4 USB 2.0 ports (2 rear + 2 via header)
VGA	▪ 1 VGA port
Others	▪ 1 COM port (rear) ▪ 2 SATA DOM power connector ▪ 1 TPM 2.0 header

Expansion Slots

PCI-Express	▪ 3 PCI-E 3.0 x8 ▪ 3 PCI-E 3.0 x16
M.2	▪ Interface: PCI-E 3.0 x4 ▪ Form factor: 2280, 22110 ▪ Key: M-key

Environmental Specifications	▪ Operating Temperature: 10°C to 35°C (50°F to 95°F) ▪ Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) ▪ Operating Relative Humidity: 8% to 90% (non-condensing) ▪ Non-operating Relative Humidity: 5% to 95% (non-condensing)

Parts List

Bulk Pack List

	Part Number	Qty	Description
H11SSL-C	MBD-H11SSL-C-B	1	H11SSL-C Motherboard
I/O Cable	CBL-0044L	2	57.5CM SATA FLAT S-S PBF
I/O Shield	MCP-260-00042-0N	1	STD I/O SHIELD FOR X9 SOCKET R SERVER MB

Retail Pack List

	Part Number	Qty	Description
H11SSL-C	MBD-H11SSL-C-O	1	H11SSL-C Motherboard
I/O Cable	CBL-0044L	2	57.5CM SATA FLAT S-S PBF
I/O Cable	CBL-0658	2	INT Mini-SAS HD CBL for PCIe SSD NVMe 12Gb/s 60cm 30AWG
I/O Shield	MCP-260-00042-0N	1	STD I/O SHIELD FOR X9 SOCKET R SERVER MB

Optional Parts List

	Part Number	Qty	Description
I/O Cable	CBL-SAST-0699	-	MINI SAS HD-4 SATA,12G,INT,75/75/90/90CM,75CM SB,28/30AWG,Ro
TPM security module	AOM-TPM-9655V	-	TPM 1.2 module with Infineon 9655, RoHS/REACH,PBF;
	AOM-TPM-9665V	-	TPM 2.0 module with Infineon 9665, RoHS/REACH,PBF;